MH2201WZ

1200V 25A Fast Recovery Diode

Datasheet

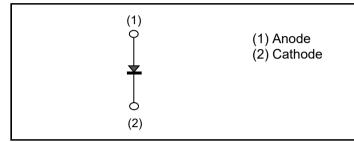
| V_{RM} | 1200V |
|-------------------------------|--------|
| I _{F (Nominal)} | 25A |
| $V_{F (Typ.)}$ | 1.65V |
| Max. Possible Chips per Wafer | 990pcs |

● Outline Wafer

Features

- 1) Light Punch Through Type
- 2) Low Forward Voltage
- 3) Very Fast & Soft Recovery
- 4) Low Recovery Loss

●Inner Circuit



Application

Free Wheeling

Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|--|--------------------|-------------|------|
| Repetitive Peak Reverse Voltage, T _j = 25°C | V_{RM} | 1200 | V |
| Forward Current | I _F *1 | *1) | А |
| Pulsed Forward Current | l _{FP} *2 | 75 | Α |
| Operating Junction Temperature | T _j | -40 to +175 | °C |

^{*1} Depending on thermal properties of assembly

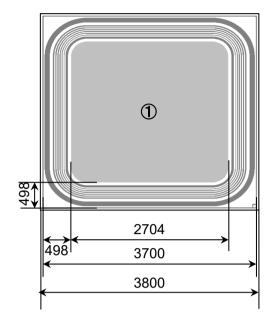
• Electrical Characteristics (at T_i = 25°C unless otherwise specified, in case of TO-247N package)

| Parameter | Symbol | ool Conditions | | Values | | Unit | |
|-------------------|-------------------|---|------|--------------|----------|-------|--|
| - Farameter | Symbol | | Min. | Тур. | Max. | Offic | |
| Breakdown Voltage | BV | I _R = 10μA | 1200 | - | - | V | |
| Reverse Current | I _R | V _R = 1200V | - | - | 10 | μΑ | |
| Forward Voltage | V _F *3 | $I_F = 25A,$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$ | - | 1.65 1.85 | 2.1 - | V | |

^{*3} Design assurance without measurement

^{*2} Pulse width limited by T_{imax.}

●Chip Information

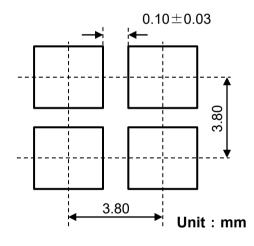


Unit: µm

: Pad Area

① : Anode Bonding Pad

Backside: Cathode



| Wafer Size | 150mm | | |
|-------------------------|-----------------------|--|--|
| Wafer Thickness | 0.12±0.01mm | | |
| Chip Size | 3.80mm×3.80mm | | |
| Cut Line Width | 0.10±0.03mm | | |
| Top Side Metallization | AlSiCu:5.0µm | | |
| Back Side Metallization | Ti/Ni:0.4µm/Au:0.05µm | | |
| Passivation | Polyimide | | |

•Further Electrical Characteristics

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

| This chip data sheet refers to the device data sheet | RGS50TSX2D |
|--|------------|
| | |

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